

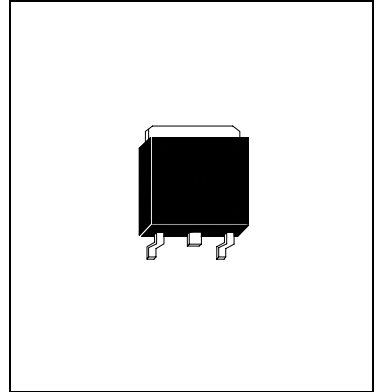


HJ3953

NPN EPITAXIAL PLANAR TRANSISTOR

Description

High-definition CRT display video output, wide-band amp,



Features

- High f_T : $f_T = 400\text{MHz}$
- High breakdown voltage: $V_{CEO} = 120\text{V}$ (min)
- Small reverse transfer capacitance and excellent HF response

Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
Storage Temperature -55 ~ +150 °C
Junction Temperature +150 °C
- Maximum Power Dissipation
Total Power Dissipation (Ta=25°C) 1.3 W
- Maximum Voltages and Currents
BVCEO Collector to Emitter Voltage 120 V
BVCBO Collector to Emitter Voltage 120 V
BVEBO Emitter to Base Voltage 3 V
IC Collector Current (DC) 200 mA

Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	120	-	-	V	IC=100uA, IE=0
BVCEO	120	-	-	V	IC=1mA, IB=0
BVEBO	3	-	-	V	IE=100uA, IC=0
ICBO	-	-	100	nA	VCB=80V, IE=0
IEBO	-	-	100	nA	VEB=2V, IC=0
*VCE(sat)	-	-	1	V	IC=30mA, IB=3mA
*VBE(sat)	-	-	1	V	IC=30mA, IB=3mA
*hFE1	60	160	320		VCE=10V, IC=10mA
*hFE2	40	-	-		VCE=10V, IC=100mA
fT	400	-	-	MHz	VCE=10V, IC=50mA
Cob	2.1	-	-	pF	VCB=30V, f=1MHz

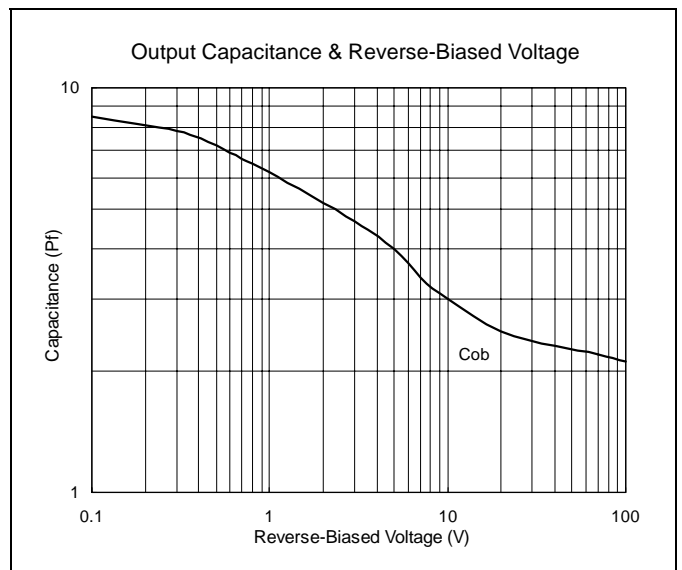
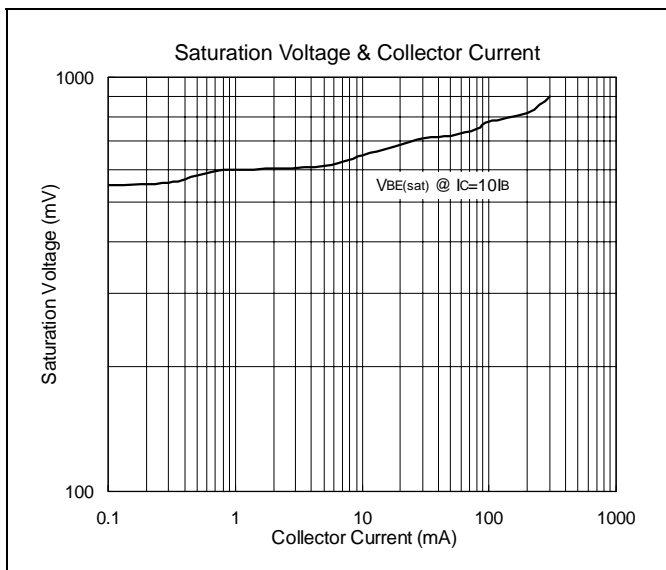
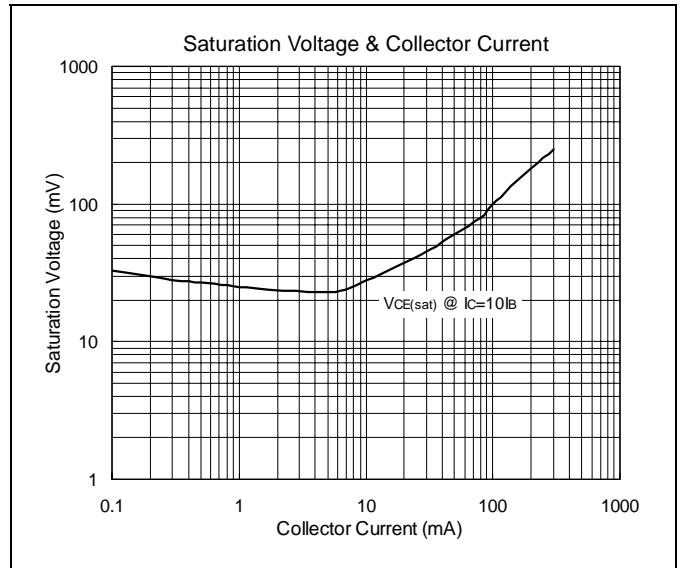
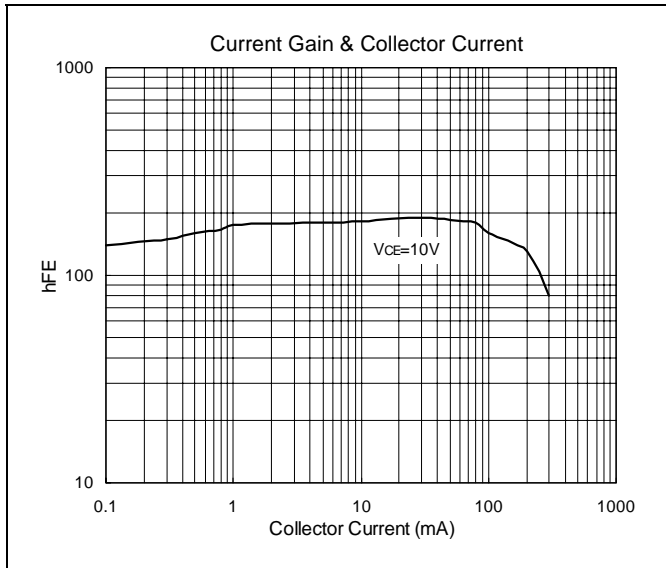
*Pulse Test : Pulse Width $\leq 380\mu\text{s}$, Duty Cycle $\leq 2\%$

Classification Of hFE1

Rank	D	E	F
Range	60-120	100-200	160-320

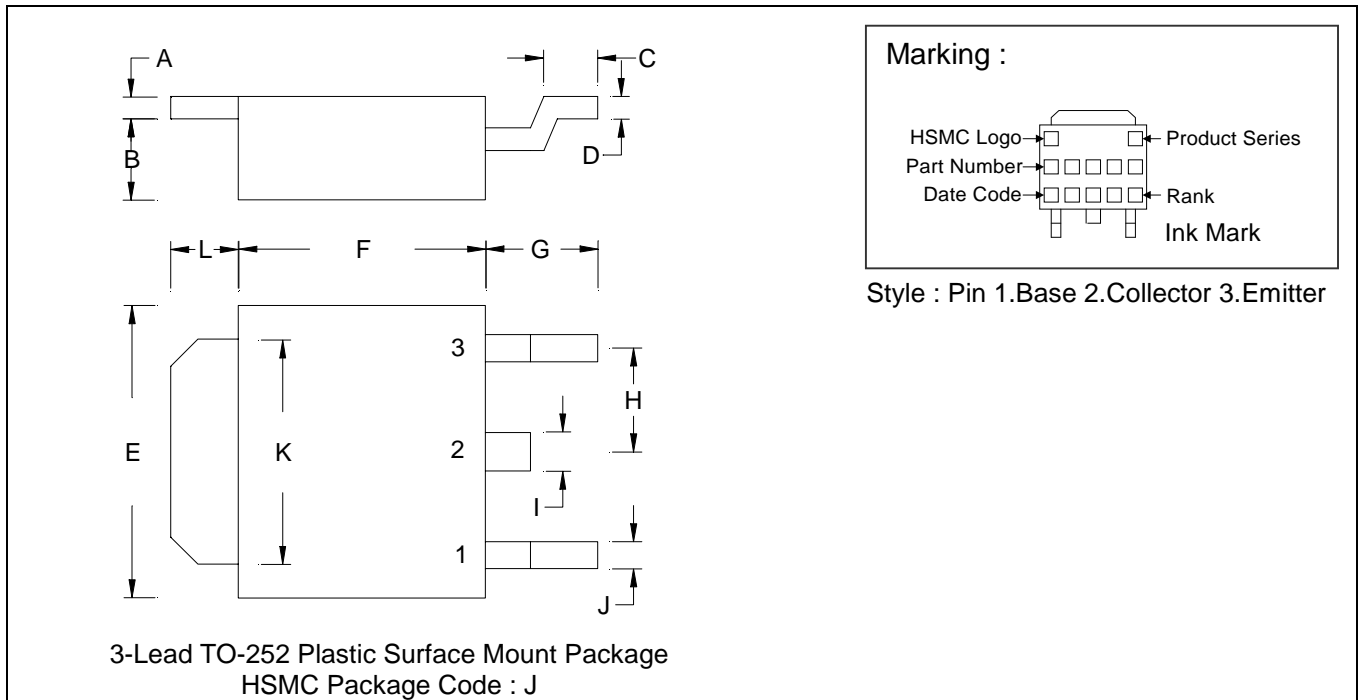


Characteristics Curve





TO-252 Dimension



*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0177	0.0217	0.45	0.55	G	0.0866	0.1102	2.20	2.80
B	0.0650	0.0768	1.65	1.95	H	-	*0.0906	-	*2.30
C	0.0354	0.0591	0.90	1.50	I	-	0.0354	-	0.90
D	0.0177	0.0236	0.45	0.60	J	-	0.0315	-	0.80
E	0.2520	0.2677	6.40	6.80	K	0.2047	0.2165	5.20	5.50
F	0.2125	0.2283	5.40	5.80	L	0.0551	0.0630	1.40	1.60

Notes : 1.Dimension and tolerance based on our Spec. dated May. 05,1996.
 2.Controlling dimension : millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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